## **LN183H**

### GaAlAs Infrared Light Emitting Diode

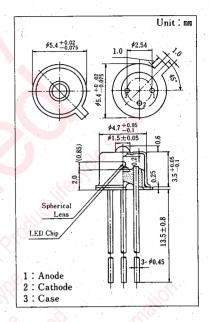
#### For Optical Fiber Communication

#### **■** Features

- High-frequency response: f<sub>C</sub>=35MHz (typ.)
- High optical fiber power for GI50/125: P<sub>f</sub>=70 µW
- Current-optical output characteristics with good linearity
- High reliability

#### ■ Absolute Maximum Ratings (Ta=25°C)

Item	Symbol	Value	Unit		
Power Dissipation	$P_{D}$	250	mW		
Forward Current	$I_{\mathbf{F}}$	150	mA		
Reverse Voltage	$V_R$	3	V		
Operating Ambient Temperature	Topr	-40~+85	°C		
Storage Temperature	Tstg	$-40 \sim +100$	i, c		



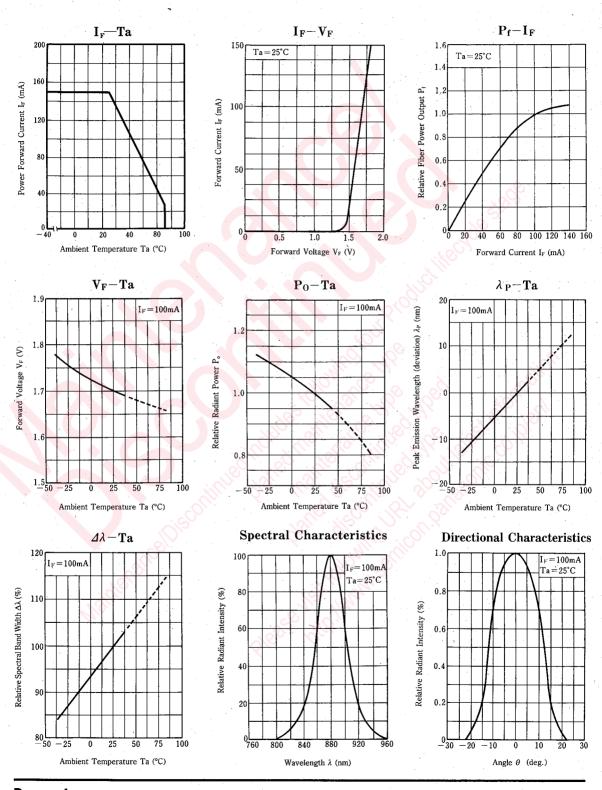
#### ■ Electro-Optical Characteristics (Ta=25°C)

Item	Symbol	Condition	min.	typ.	max.	Unit
Optical Power Output	Po	I <sub>F</sub> =100 mA	2.1	3		mW
Peak Emission Wavelength	λp	I <sub>F</sub> =100 mA	100	880		nm
Spectral Band Width	Δλ	I <sub>F</sub> =100 mA		45		nm
Forward Voltage (DC)	$V_{\rm F}$	I <sub>F</sub> =100 mA	00	1.7	2	V
Reverse Current (DC)	$I_R$	V <sub>R</sub> =3 V			10	μA
Beam Half Angle	θ*	I <sub>F</sub> =100 mA		25		deg.
Cutoff Frequency	f <sub>C</sub> **	$I_F = 50 \text{ mA} + 17.5 \text{ mAp-p}$		35		MHz
Fiber Power Output	P <sub>f</sub> ***	I <sub>F</sub> =100 mA	50	70		μW

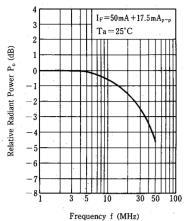
<sup>\*:</sup> Angle measured from the optical axis to the half power point.

\*\*: Frequency when modulation light power decreases by 3dB from 1MHz.  $\left(10 \log \frac{P_0(f_c \, MHz)}{P_0(1 \, MHz)} = -1 \right)$ 

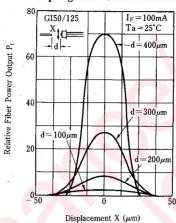
<sup>\*\*\*:</sup> Light power at GI50/125.







#### **Coupling Loss Characteristics**



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